



Global Communication Semiconductors, LLC

Corporate & Foundry

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Website: www.gcsincorp.com

Job Title: **Process Engineer - Backside**
Job Req. #0669
Department: Manufacturing Engineering
Status: Day

Job Description

Supports pre-production, develops new processes, installs new processes, qualifies new processes, implements improvements into production flow, and handles details of ramping up of chosen products. Must have a good understanding of III-V compound semiconductor device and the overall process technologies, and have a grasp of the wafer process flow from beginning of the front side process to the backside.

This engineer will be expected to interface with and able to follow/move the lots through all areas of the GCS compound semiconductor FAB. Key areas of focus will be finding the process windows to center the processes on new products, establishing new design rules, evaluation of yields, and analysis of failures as the product goes through the transition phase from development to production.

- Responsible for the backside of wafer processing
- Handles daily disposition of wafers
- Backside photo process along with ownership of contact printers

Job Requirements

- Bachelor's in science or engineering preferred
- Minimum of 3-5 years of work experience in related field
- In-depth knowledge with respect to plating and 1x printers
- Knowledge and experience to improve plating process
- Understand the backside processing with thinned wafers
- Hands-on experience in semiconductor processing and metrology equipment
- Familiar with the process flows of various starting material/process/products
- Experience with statistical analysis and design of experiments
- Process optimization/qualification experience
- Excellent written and communication skills
- Able to multi-task and work quickly